

Specification Sheet for Approved

Customer Name:	
Customer Part No.:	
Ceaiya Part No:	CCM7060A Series
Spec No:	L7060A

【For Customer Approval Only】

If you Approval, Please Stamp

【RoHS Compliant Parts】

pproved By	Checked By	Prepared By
李庆辉	刘志坚	劳水花

Shenzhen Ceaiya Electronics Co., Ltd.

地址 1: 深圳市龙华区观湖街道鹭湖社区观盛二路 5 号捷顺科技中心 B706

地址 2: 广东省东莞清溪镇青滨东路 105 号力合紫荆智能制造中心 10 栋

Http://www.szceaiya.com

Tel: 0769-89135516

Fax: 0769-89135519

【Version of Changed Record】

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
A0	2023-12-11	New release	/	Li qing hui

1. Scope

This specification applies to the CCM7060A Series of wire wound SMD Common Mode Filter.

2. Product Description and Identification (Part Number)

CCM 7060 A - 701
① ② ③ ④

- ① Series
- ② Dimension
- ③ Serial number
- ④ Impedance 701=700Ω

3. Shape and Dimensions (Unit:mm)

Dimensions and recommended PCB pattern for reflow soldering, please see Fig4-1 and Table4-1

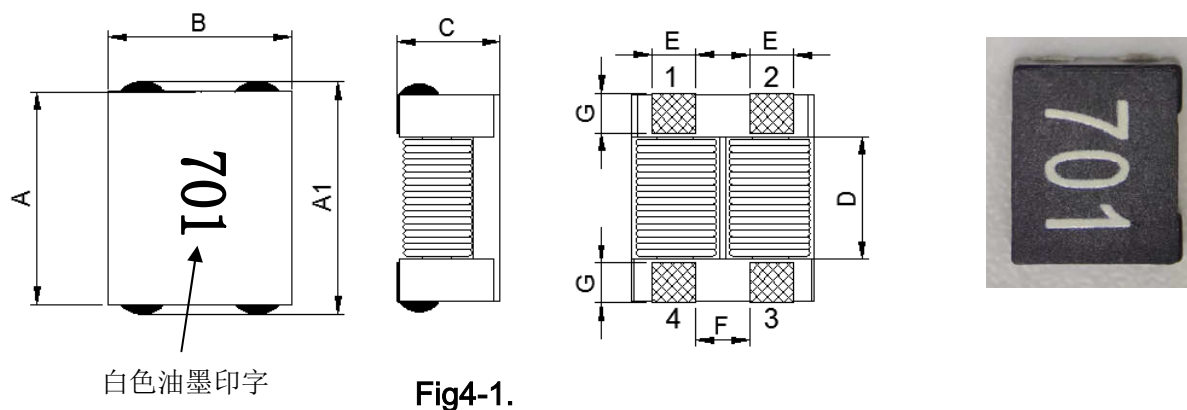


Table 4-1.

A	A1	B	C	D	E	F	G
7.6Max.	7.5± 0.5	6.0 ± 0.5	3.5±0.3	3.5Typ.	1.5 Typ.	1.5 Typ.	1.7 Typ.

4. Electrical Characteristics

Part No.	Z(Ω) 100MHz/0.1V		RDC(mΩ) Max[1 line]	Rated Current (A) Max	IR(MΩ) Min	Rated Voltage (V) Max	Making
	Min	Typ.					
CCM7060A-101	100	140	10	9.0	10	80	101
CCM7060A-301	225	300	10	5.0	10	80	301
CCM7060A-501	275	450	10	5.0	10	80	501
CCM7060A-601	500	700	15	4.0	10	80	601
CCM7060A-701	500	700	15	4.0	10	80	701
CCM7060A-102	800	1020	17	3.0	10	80	102
CCM7060A-132	910	1300	21	2.5	10	80	132
CCM7060A-272	2000	2700	63	1.0	10	80	272
CCM7060A-302	2500	3000	75	0.9	10	80	302

※ Measurement Equipment:

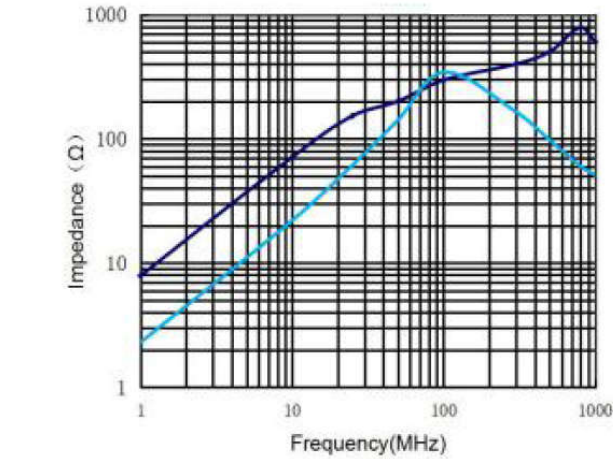
Common mode impedance $z(\Omega)$: 4991A

DC resistance : HIOKI3540

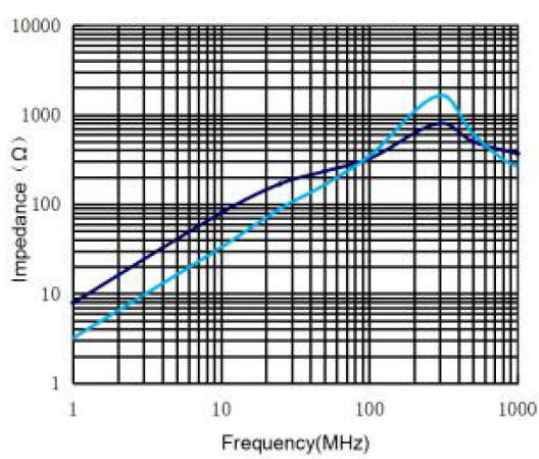
Insulation resistance: Chroma 19053

5. TYPICAL ELECTRICAL CHARACTERISTICS

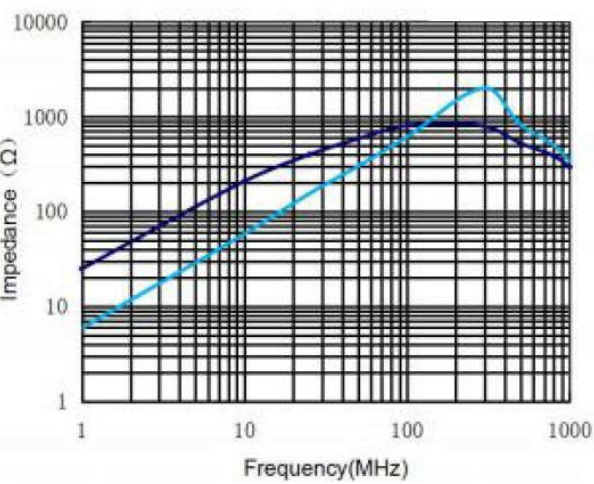
CCM7060A-101



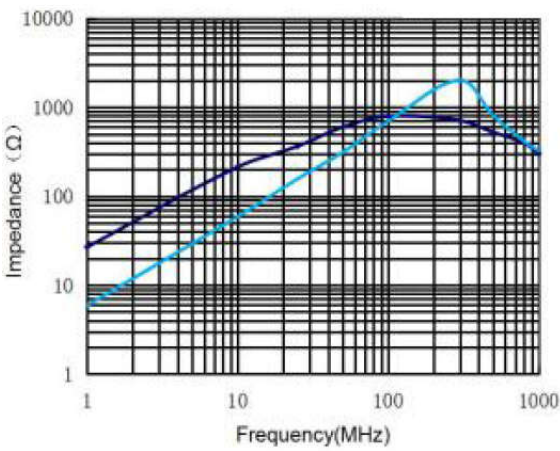
CCM7060A-301



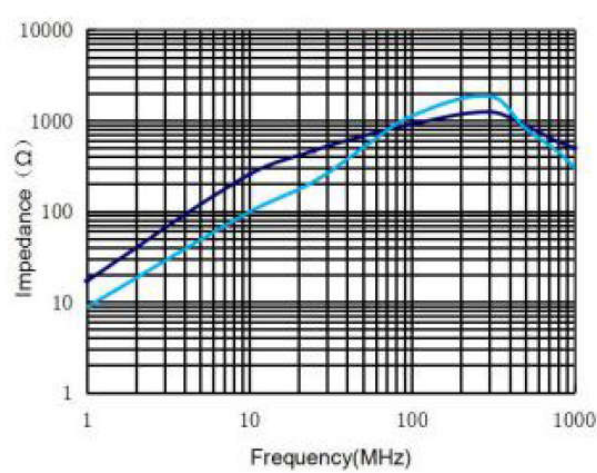
CCM7060A-501



CCM7060A-701

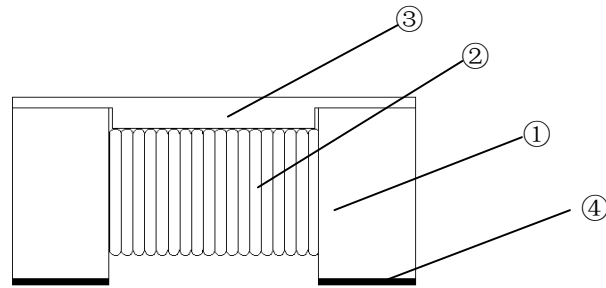


CCM7060A-102



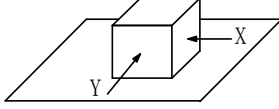
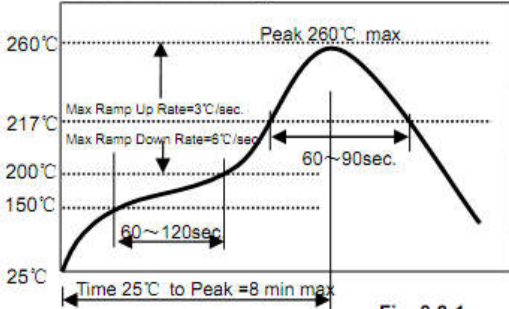
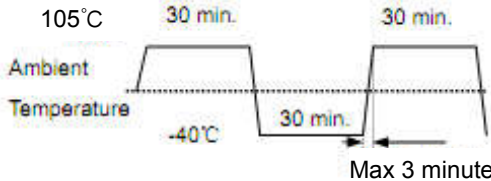
6. Structure

The structure of CCM7060 product.

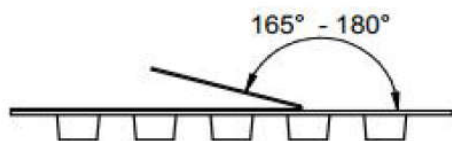
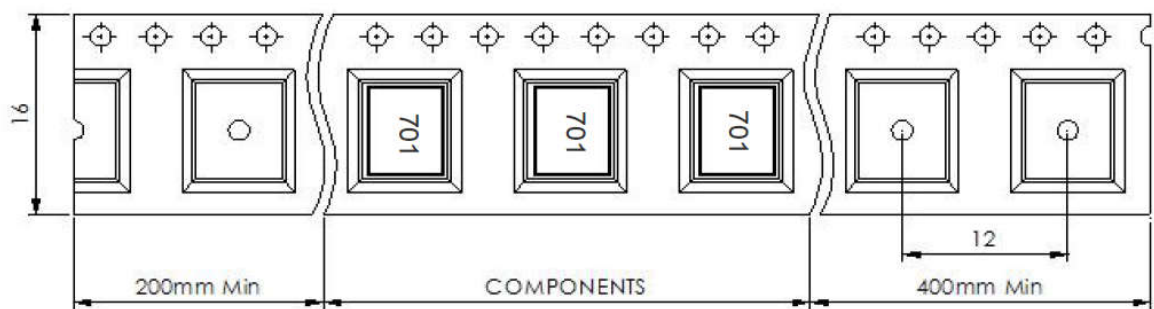


No.	Part name	Material	Ceaiya P/N
①	Drum Core	Ni-Zn Ferrite Core	BQ/YX
②	Wire	Polyurethane enameled copper wire	YLSL
③	Case	LCP	ZX
④	Electrode	Cu + Sn plating	CZ

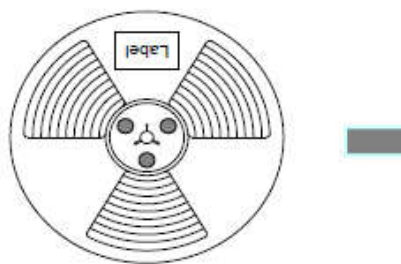
7. Reliability Test

Items	Requirements	Test Methods and Remarks
7.1 Terminal Strength	No removal or split of the termination or other defects shall occur.  Fig.7.1-1	1) Solder the inductor to the testing jig (glass epoxy board shown in Fig.7.1-1) using eutectic solder. Then apply a force in the direction of the arrow. 2) 10N force. 3) Keep time: 5±2s
7.2 High Temperature	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :125+/-5°C 2) Duration : 96 ±4 Hours 3) Recovery : then measured at room ambient temperature after placing 24 hours.
7.3 Low Temperature	1. No visible mechanical damage 2. Inductance change: Within ±10%	1) Temperature and time: -40±5°C 2) Duration: 96±4 hours 3) Recovery : then measured at room ambient temperature after placing 24 hours.
7.4 Vibration test	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Frequency range:10Hz~55Hz~10Hz 2) Amplitude:1.5mm p-p 3) Direction:X,Y,Z 4) Time:1 minute/cycle,2hours per axis
7.5 High Temperature Storage Tested	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :60+/-2°C 2) Relative Humidity :90-95% RH 3) Duration : 96 ±4 Hours 4) Recovery : then measured at room ambient temperature after placing 24 hours.
7.6 Resistance to Soldering Heat	1. No visible mechanical damage. 2. Inductance change: Within ±10%  Fig.7.6-1	1) Re-flowing Profile: Please refer to Fig.7.6-1 2) Test board thickness: 1.0mm 3) Test board material: glass epoxy resin 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring
7.7 Thermal Shock	1. No visible mechanical damage. 2. Inductance change: Within ±10%  Fig.7.7-1	1) Temperature and time: -40±3°C for 30±3 min→105°C for 30±3min, please refer to Fig.7.7-1. 2) Transforming interval: Max, 3 minutes 3) Tested cycle: 100 cycles 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring

8.Packaging and Marking:



Tape width	Distance	Pull-of force
16 mm	12 mm	10~120g



轮盘：13’（直径330mm）
数量：1500PCS/ 盘

Packaging Quantity:
1.5KPCS/ Reel